

ECD Product Advisory - Addition of Foxconn Vietnam as Alternate Manufacturing Site for Emulex FC HBAs

Issue Date: 27-September-2021

Change Description:

Addition of Foxconn Vietnam as a contract manufacturing site for all Emulex Fibre Channel (FC) Host Bus Adapters (HBAs), including standard/Emulex-branded and OEM models, for additional capacity and supply chain continuity

Parts Affected:

All Emulex Gen6 16GFC and 32GFC (Lancer G6-based) HBAs:

- LPe31000-series (Gen6 16GFC) – All Emulex-branded and corresponding OEM derivative and custom HBAs
- LPe32000-series (Gen6 32GFC) – All Emulex-branded and corresponding OEM derivative and custom HBAs

All Emulex Gen7 32GFC and 64GFC (Prism-based) HBAs:

- LPe35000-series (Gen7 32GFC) – All Emulex-branded and corresponding OEM derivative and custom HBAs
- LPe36000-series (Gen7 64GFC) – All Emulex-branded and corresponding OEM derivative and custom HBAs

Description and Extent of Change:

Broadcom Emulex Connectivity Division (ECD) currently sources FC HBAs from a contract manufacturer (CM) named Flextronics Penang in Malaysia. Due to increased demand and to ensure supply chain continuity, Broadcom ECD is adding an additional contract manufacturer - Foxconn Vietnam. The same component (PCBs, Memory, etc.) vendors currently used at Flextronics Penang will be used at Foxconn Vietnam.

The CM location is traceable through the board serial number. The letters "FV" at the suffix of the serial number

Indicates a Foxconn Vietnam manufactured board product. Below is an illustrative board label example and the factory address for Foxconn Vietnam:



Funing Precision Component Co., Ltd Lot B

Que Vo Industrial Zone, Nam Son Ward

Bac Ninh City, Bac Ninh Province, 35000 Viet Nam

Reasons for Change:

Emulex Connectivity Division (ECD) is proactively expanding the manufacturing supplier base for FC HBAs to safeguard availability. Foxconn Vietnam is already an approved Broadcom manufacturing site and has met all required quality control processes and is a manufacturing supplier for other Broadcom board-level products.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

- No form/fit/functional hardware changes to the PCB or PCBA
- HBA functional and performance specifications remain the same

Recommended Action by the Customer:

- Acknowledge this Product Advisory and ensure your respective Receiving Inspection departments are prepared to receive products from Foxconn Vietnam
- For OEM products, if a new site code is required for customer labeling to indicate assembly location, please work with your Broadcom ECD contacts to update custom labels as needed

Effective Date of Change:

Product shipments using this change will begin after January 1st, 2022. Timing of shipment of the board products will vary by part number depending on customer demand and inventory levels.

Qualification Data:

Electronic First Article Inspection (eFAI) Reports for initial production builds will be available on request

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please acknowledge the receipt of the notice within 30 days of delivery. Lack of acknowledgement within 30 days constitutes acceptance of the change per JEDEC J-STD-046.

